



## Product Change Notice

Micron PCN: 30411  
 Date: 2/10/2011

<b>Type of Change:</b>	Die Shrink, End of Life	
<b>Title of Change:</b>	256Mb and 288Mb RLDRAM (F26A) Die Shrink/EOL	
<b>Description of Change:</b>	Micron's 115nm 288Mb RLDRAM (F26A) is being replaced by a 50nm process technology (F66A). The 256Mb density RLDRAM is being discontinued.	
<b>Reason for Change:</b>	Optimization of Manufacturing Efficiency	
<b>Contact Information:</b>	<u>Marketing Contact</u> SHERRY GRAY <a href="mailto:SGRAY@MICRON.COM">SGRAY@MICRON.COM</a> Micron Technology, Inc.	<u>Engineering Contact</u> BRIAN GROSS <a href="mailto:BGROSS@MICRON.COM">BGROSS@MICRON.COM</a> Micron Technology, Inc.

**Product Affected:** All 115nm 256Mb and 288Mb RLDRAM (F26A) based products

	<b>Affected Micron Part Number</b>	<b>Replacement Part Number</b>
<b>256Mb Density</b>		
<b>16x16</b>		
	MT49H16M16FM-33	Contact Factory
	MT49H16M16FM-5	Contact Factory
<b>8x32</b>		
	MT49H8M32FM-33	Contact Factory
	MT49H8M32FM-5	Contact Factory
	MT49H8M32BM-5	Contact Factory
<b>288Mb Density</b>		
<b>8x36 CIO</b>		
	MT49H8M36BM-25	MT49H8M36BM-25:B
	MT49H8M36BM-25 IT	MT49H8M36BM-25 IT:B
	MT49H8M36BM-33	MT49H8M36BM-33:B
	MT49H8M36BM-33 IT	MT49H8M36BM-33 IT:B
	MT49H8M36BM-5	MT49H8M36BM-33:B
	MT49H8M36BM-TI	MT49H8M36BM-TI:B
	MT49H8M36FM-25	MT49H8M36FM-25:B
	MT49H8M36FM-25 IT	MT49H8M36FM-25 IT:B
	MT49H8M36FM-33	MT49H8M36FM-33:B
	MT49H8M36FM-33 IT	MT49H8M36FM-25 IT:B
	MT49H8M36FM-5	MT49H8M36FM-33:B
<b>16x18 CIO</b>		
	MT49H16M18BM-25	MT49H16M18BM-25:B
	MT49H16M18BM-33	MT49H16M18BM-33:B
	MT49H16M18BM-33 IT	MT49H16M18BM-25 IT:B
	MT49H16M18BM-5	MT49H16M18BM-33:B
	MT49H16M18FM-25	MT49H16M18FM-25:B
	MT49H16M18FM-33	MT49H16M18FM-33:B

Note: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change



MT49H16M18FM-33 IT	MT49H16M18FM-25 IT:B
MT49H16M18FM-5	MT49H16M18FM-33:B
<b>32x9 CIO</b>	
MT49H32M9BM-25	MT49H32M9BM-25:B
MT49H32M9BM-33	MT49H32M9BM-33:B
MT49H32M9FM-25	MT49H32M9FM-25:B
MT49H32M9FM-33	MT49H32M9FM-33:B
MT49H32M9FM-5	MT49H32M9FM-33:B
<b>16x18 SIO</b>	
MT49H16M18CBM-25	MT49H16M18CBM-25:B
MT49H16M18CBM-33	MT49H16M18CBM-25:B
MT49H16M18CBM-33 IT	MT49H16M18CBM-25 IT:B
MT49H16M18CBM-5	MT49H16M18CBM-25:B
MT49H16M18CFM-25	MT49H16M18CFM-25:B
MT49H16M18CFM-33	MT49H16M18CFM-33:B
MT49H16M18CFM-33 IT	MT49H16M18CFM-25 IT:B
MT49H16M18CFM-5 IT	MT49H16M18CFM-25 IT:B
MT49H16M18CFM-5	MT49H16M18CFM-33:B

**Method of Identification:**

The die designator "B" has been added to the end of the marketing part number. Please see example below.

<u>Affected Micron Part Number</u>	<u>Replacement Part Number</u>
MT49H8M36BM-33	MT49H8M36BM-33: <b>B</b>

**Manufacturing Sites Affected**

**50nm Product (F66A)**

*Fabrication:* Singapore

*Assembly:* Japan

**Product/Data Availability**

**50nm Product (F66A)**

<u>F66A Config</u>	<u>Samples Available</u>	<u>Qual Data Available</u>	<u>Production Available</u>
8x36 CIO	April 2011	May 2011	May 2011
16x18 CIO	April 2011	May 2011	May 2011
32x9 CIO	May 2011	June 2011	June 2011
16x18 SIO	June 2011	July 2011	July 2011

**95nm Product (F26A)**

*Last Time Buy:* December 31, 2011

*Last Time Ship:* June 30, 2012

Note: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change